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**InvesTech Holdings Limited**

**威訊控股有限公司**

*(Incorporated in the Cayman Islands and continued in Bermuda with limited liability)*

**(Stock Code: 1087)**

**SUPPLEMENTAL ANNOUNCEMENT  
IN RELATION TO  
PLACING OF NEW SHARES UNDER GENERAL MANDATE**

**Placing Agent**



**結好融資有限公司**  
**GET NICE CAPITAL LIMITED**

Reference is made to the announcement of InvesTech Holdings Limited (the “**Company**”) dated 16 August 2021 (the “**Announcement**”) in relation to the Placing. Unless the context otherwise requires, capitalised terms used in this announcement shall have the same meanings as those defined in the Announcement.

The Board would like to provide additional information regarding the intended use of proceeds from the Placing.

**CLARIFICATION ON THE USE OF PROCEEDS**

As set out in the Announcement, assuming that the Placing is completed on the basis that the maximum of 14,040,000 Placing Shares have been placed via the Placing Agent to no less than six Places, the maximum net proceeds from the Placing will be approximately HK\$16.83 million (representing a net issue price will be approximately HK\$1.20 per Placing Share). The following table sets out the intended use of the net proceeds:

<b>Intended use of net proceeds</b>	<b>Net proceeds (approximate) (HK\$)</b>	<b>Percentage of net proceeds</b>
General working capital	7.63 million	45.34%
Financing the business development of the Group	1.20 million	7.13%
Repayment of bank and other borrowings of the Group	<u>8.00 million</u>	<u>47.53%</u>
<b>Total:</b>	<b><u>16.83 million</u></b>	<b><u>100.00%</u></b>

In light of the increasing market competition and volatile economy owing to the continuation of the coronavirus (COVID-19) pandemic, and the global shortage of semiconductor products which may cause longer sales cycles and hence higher working capital requirement, the Board considered that the Group shall maintain sufficient liquidity to increase its operational flexibility and to sustain its capability for financing any of its potential business development opportunities upon the Group's existing business, being its core business of IT infrastructure system integration, as and when suitable opportunity arises, and for the use of general working capital of the Group. Through the Placing, the Group is able to increase its working capital without (i) increasing the interest burden on the Group; and (ii) affecting the financial position and the liquidity risk of the Group by means of equity fundraising.

Slightly less than half of the above net proceeds are to be utilised for the repayment of the Group's bank and other borrowings as the Directors are of the view that the reduction of debt financing for the Group will correspondingly reduce the ongoing interest expenses of the Group, which may positively influence the profitability of the Group, and with the decrease of the Group's gearing ratio, the Group's financial position will in turn be improved.

By Order of the Board  
**InvesTech Holdings Limited**  
**Chan Sek Keung, Ringo**  
*Chairman and Chief Executive Officer*

Hong Kong, 27 August 2021

*As at the date of this announcement, the executive Directors are Mr. Chan Sek Keung, Ringo (Chairman and Chief Executive Officer), Ms. Wang Fang, Mr. Lu Chengye and Mr. Liu Chun Fai, the non-executive Director is Mr. Wong Tsu Wai, Derek, and the independent non-executive Directors are Mr. David Tsoi, Mr. Lu, Brian Yong Chen and Mr. Yuen Shiu Wai.*